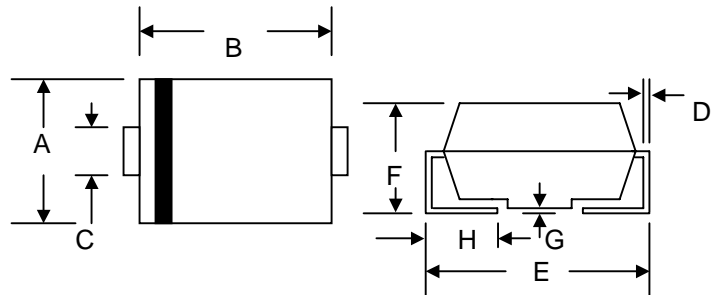


Data Sheet 2843, Rev.-

Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 50A Peak
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability
- Classification Rating 94V-O



Mechanical Data

- Case: Low Profile Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.093 grams (approx.)

SMB/DO-214AA				
Dim	Min	Max	Min	Max
A	3.30	3.94	0.130	0.155
B	4.06	4.70	0.160	0.185
C	1.91	2.11	0.075	0.083
D	0.15	0.31	0.006	0.012
E	5.08	5.59	0.200	0.220
F	2.13	2.44	0.084	0.096
G	0.05	0.20	0.002	0.008
H	0.76	1.27	0.030	0.050
	In mm		In inch	

Maximum Ratings and Electrical Characteristics @_{T_A}=25°C unless otherwise specified

Characteristic	Symbol	SK22	SK23	SK24	SK25	SK26	SK28	SK29	S210	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	20	30	40	50	60	80	90	100	V
Working Peak Reverse Voltage	V _{RWM}									
DC Blocking Voltage	V _R									
RMS Reverse Voltage	V _{R(RMS)}	14	21	28	35	42	56	64	71	V
Average Rectified Output Current @ _{T_L} = 105°C	I _O	2.0								A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50								A
Forward Voltage @ _{I_F} = 2.0A	V _{FM}	0.55		0.70		0.85			V	
Peak Reverse Current @ _{T_A} = 25°C At Rated DC Blocking Voltage @ _{T_A} = 100°C	I _{RM}					0.5				mA
						20				
Typical Thermal Resistance Junction to Ambient (Note 1)	R _{THJA}	75								°C/W
Operating Temperature Range	T _J	-65 to +125								°C
Storage Temperature Range	T _{STG}	-65 to +150								°C

Note: 1. Mounted on P.C. Board with 8.0mm² copper pad areas

Data Sheet 2843, Rev. -

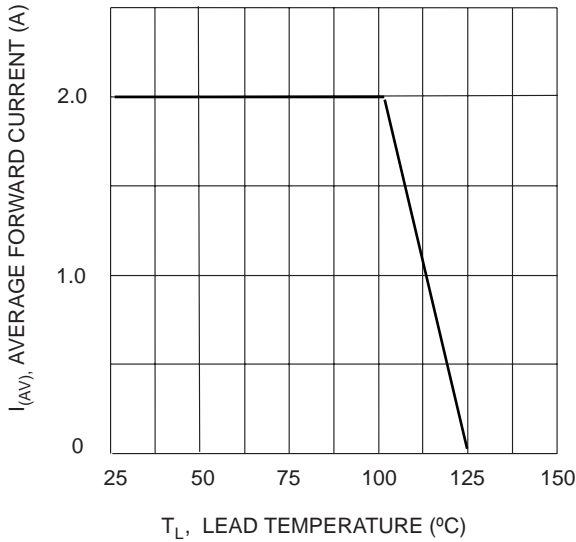


Fig. 1 Forward Current Derating Curve

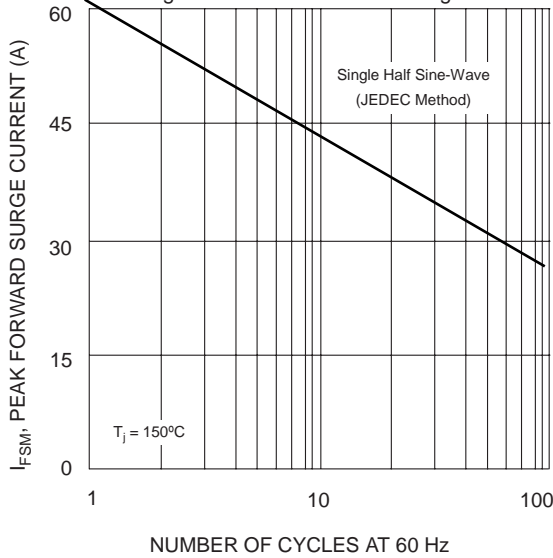


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

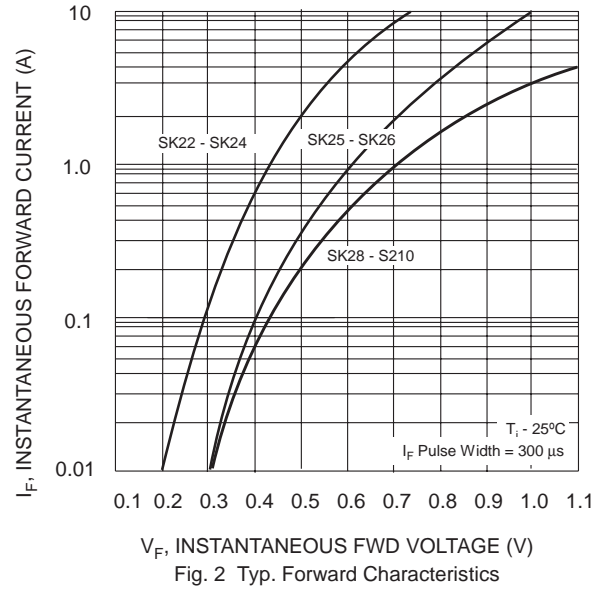


Fig. 2 Typ. Forward Characteristics

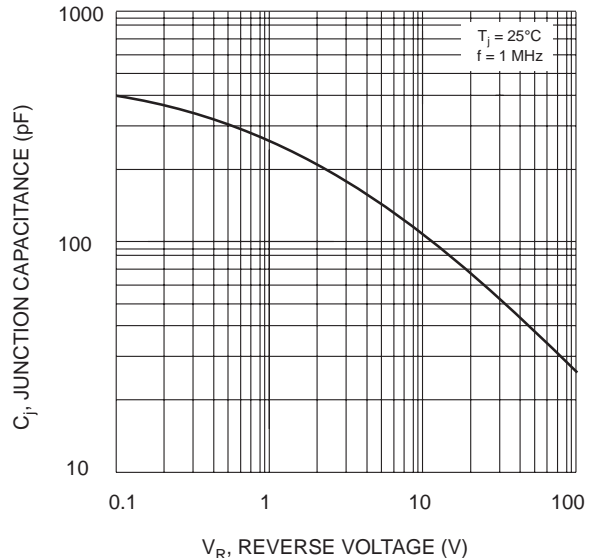


Fig. 4 Typical Junction Capacitance

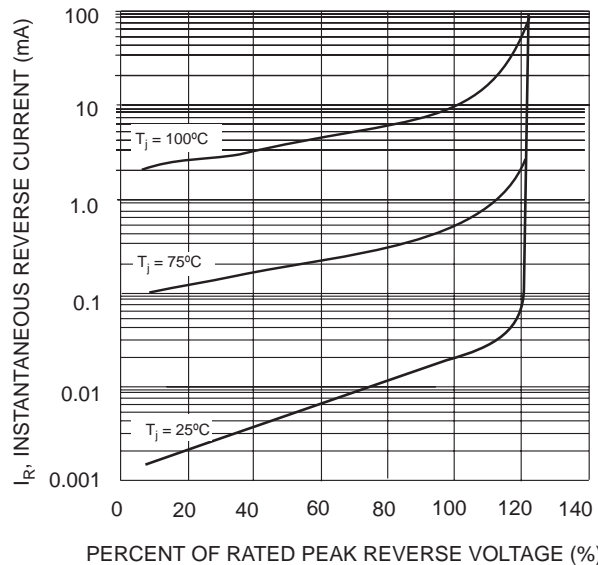


Fig. 5 Typical Reverse Characteristics

TECHNICAL DATA

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